	CONNECTING CS INDUSTRIES® international and Par	PC, Bannockb	urn, Illinois. A	.ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration	tion of t encomp	he substances basses all low	within the er level ma	manufactur terials for wl	er listed it hich the m	em. Note: it anufacturer	f the item is an as has engineering	sembly with lowe responsibility.	
1752-21.1					Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	ials and Mfg Information				
Supplie	r Information															
Company	name*	Company unique ID				Unique ID Authority					Response Date*					
nsemi												2022-02-10				
Contact N	lame	Title - Contact				Phone - Contact*				Email - Contact*						
Product-l	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item Nur   FQPF3N80C		n Number Mfr Item Name				Effective Date	ate Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type		
			80C	QFC 800V 4.80hm TO220F			2022-02-10 CPA			2112.34		mg	Each			
/Ianufa	cturing Proccess Information	tion														
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-02		-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Ten		Temperati	ire Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		<b>30</b> se		second	ls 3						
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.01	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			А	Lead (Pb)	7439-92-1	7a	3.7494	mg
			Supplier	Tin (Sn)	7440-31-5		0.2005	mg
Lead Frame	1294.26	mg	Supplier	Tin (Sn)	7440-31-5		1.2943	mg
			Supplier	Copper (Cu)	7440-50-8		1292.9657	mg
Iold Compound-Black	784.93	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		7.8493	mg
			Supplier	Brominated Epoxy Resin-2	68541-56-0		7.8493	mg
			Supplier	Proprietary	Proprietary Data		39.2465	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		7.8493	mg
			Supplier	Carbon Black (C)	1333-86-4		3.9246	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		121.6641	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.2465	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.2465	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		518.0538	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg